- Inputs Are TTL-Voltage Compatible
- Applications Include:

Buffer/Storage Registers Shift Registers Pattern Generators

- Flow-Through Architecture Optimizes PCB Layout
- Multiple Center-Pin V_{CC} and GND Configurations Minimize High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1-μm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Small-Outline Packages and Standard Plastic 300-mil DIPs

(TOP VIEW)								
1Q [1	U 24	CLR					
2Q [2	23	1D					
3Q [3	22	2D					
4Q [4	21] 3D					
GND [5	20	4D					
GND [6	19						
GND [7	18] Vcc					
GND [8	17	5D					
5Q [9	16	6D					
6Q [10	15	7D					
7Q [11	14	BD [
8Q [12	13	CLK					

DW OR NT PACKAGE

description

These positive-edge-triggered flip-flops implement D-type flip-flop logic with a direct clear input.

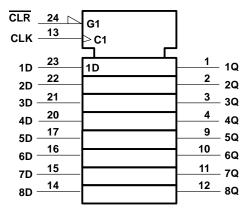
Data at the D inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse. When the clock input is at either the high or low level, the D input signal has no effect at the output.

The 74ACT11273 is characterized for operation from – 40°C to 85°C.

FUNCTION TABLE

	INPUTS	OUTPUT	
CLR	CLOCK	D	Q
L	Х	Х	L
Н	\uparrow	Н	Н
Н	\uparrow	L	L
Н	L	Χ	Q_0

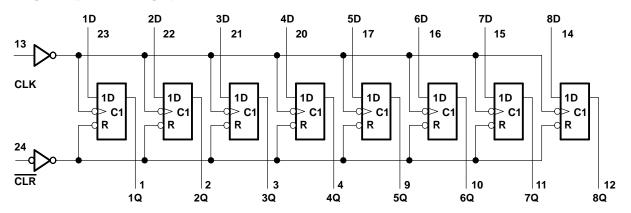
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	– 0.5 V to 7 V
Input voltage range, V _I (see Note 1)	\dots – 0.5 V to V _{CC} + 0.5 V
Output voltage range, V _O (see Note 1)	$- 0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	$\dots \dots \pm 50 \text{ mA}$
Continuous output current, I _O (V _O = 0 to V _{CC})	$\dots \dots \pm 50 \text{ mA}$
Continuous current through V _{CC} or GND	$\dots \dots \pm 200 \text{ mA}$
Storage temperature range	– 65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	V
V_{IH}	High-level input voltage	2		V
V_{IL}	Low-level input voltage		0.8	V
٧ _I	Input voltage	0	VCC	V
۷o	Output voltage	0	VCC	V
IOH	High-level output current		-24	mA
loL	Low-level output current		24	mA
Δt/Δν	Input transition rise or fall rate	0	10	ns/V
T _A	Operating free-air temperature	- 40	85	°C



NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T _A = 25°C			MIN	MAV	UNIT
PARAMETER	TEST CONDITIONS	vcc	MIN	TYP	MAX	IVIIIV	0.1 0.1 0.44 0.44 1.65 ±1 80	UNIT
	I _{OH} = - 50 μA	4.5 V	4.4			4.4		
	10H = - 30 μΑ	5.5 V	5.4			5.4		
Voн	I _{OH} = – 24 mA	4.5 V	3.94			3.8		V
	10H = - 24 IIIA	5.5 V	4.94			4.8		
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V				3.85		
	Ι _Ο L = 50 μΑ	4.5 V			0.1		0.1	
	ΙΟΓ = 20 μν	5.5 V			0.1		0.1	
V _{OL}	lo 24 mA	4.5 V			0.36		0.44	V
	I _{OL} = 24 mA	5.5 V			0.36		0.44	
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V					1.65	
II	$V_O = V_{CC}$ or GND	5.5 V			± 0.1		± 1	μΑ
ICC	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		80	μΑ
ΔlCC [‡]	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			0.9		1	mA
Ci	$V_I = V_{CC}$ or GND	5 V		4				pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

timing requirements over recommended ranges of supply voltage and operating free-air temperature range (unless otherwise noted) (see Figure 1)

	PARAMETER				MIN	MAY	UNIT
	PARAMETER		MIN	MAX	MIN MAX		UNII
fclock	Clock frequency		0	85	0	85	MHz
	Dulas duration	CLR low	5		5		
t _W	Pulse duration	CLK high or low	5.9		5.9		ns
		Data high	4		4		
t _{su}	Setup time before CLK↑	Data low	5	5	5		ns
	CLR inactive		4		4		
t _h	Hold time after CLK↑		1		1		ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	T _A = 25°C			MIN	MAX	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	IVIIIN	WAX	UNII
f _{max}			85			85		MHz
^t PHL	CLR	Any Q	4.4	9.5	12	4.4	13.3	ns
^t PLH	CLK	Δην. Ο	5.4	9.4	11.4	5.4	13.1	
^t PHL	OLK	Any Q	6	10.3	12.5	6	14.1	ns

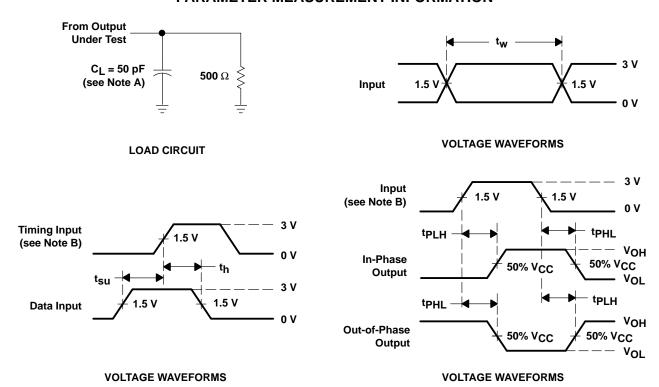
operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	$C_L = 50 \text{ pF}, \qquad f = 1 \text{ MHz}$	73	pF



[‡]This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V to V_{CC}.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \ \Omega$, $t_f = 3 \ ns$, $t_f = 3 \ ns$.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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